



AOS Thermal Compounds

NEW! MICRO-FAZE[®] C-10*Dry-to-touch Thermal Pad*Product Code: **52047-X**

TECHNICAL DATA SHEET*



THERMALLY CONDUCTIVE, HIGH PERFORMANCE PAD

Product Description

MICRO-FAZE[®] C-10 is a revolutionary dry-to-touch thermal pad formulated with **non-silicone thermal grease**. It was developed by AOS to offer the **lowest thermal resistance** in a thermal interface at this thickness without the mess of grease. MICRO-FAZE C-10 consists of a 2 mil **copper substrate** coated on both sides with specially formulated thermal grease (non-silicone, non-wax-based) that is naturally tacky but dry to the touch. It offers high heat transfer to devices with larger footprints required fill in gaps of 6 – 9 mil.

Product Features & Benefits

- MICRO-FAZE C-10 retains all the unique advantages of higher thermal performance silicone-based thermal greases but in the form of a thermal interface pad.
- Unlike phase change materials, MICRO-FAZE C-10 requires **relatively low force** to achieve total interface contact and **heat transfer starts at 25°C**.
- MICRO-FAZE C-10 allows for **total “wetting action”** to fill all microscopic surface voids without changing phase.
- A positive coefficient of thermal expansion increases the wetting action for total interface contact.
- Offers maximum heat transfer capability.
- Excellent replacement for phase change materials and silicone pads.
- MICRO-FAZE C-10 is a **“drop-in-place”** product for easy handling in a manufacturing environment.
- **Naturally tacky** film improves thermal performance and does not compromise other components.
- **Thixotropic** nature prevents run out.

Availability

MICRO-FAZE[®] C-10 appears as a non-silicone, dark grey grease on a metallic copper substrate and is available in rolls and can be die-cut to your exact specifications.

Typical Properties

Physical Properties	Value	Test Method
Substrate	Copper	----
Substrate Thickness, in.	0.002	----
Compound Thickness/side, in.	0.0035	----
Total Thickness, in.	0.009	----
Thermal & Electrical Properties	Measured @	
	36 °C	
Thermal Resistance, °C in ² /W		
@ 30 psi	0.150	ASTM D-5470 (modified)
@ 70 psi	0.104	ASTM D-5470 (modified)

**Preliminary Technical Data Sheet*